

LTM2887 32BGA 15mm X 11.25mm X 3.42mm (TABLE OF MATERIAL DECLARATION)

This product is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	BT, AUS308	0.1080	Cured thermosetting resin (including inorganic filler)	Trade secret	0.02160	20.00
				Continuous Filament Fiber Glass	65997-17-3	0.01620	15.00
				Copper	7440-50-8	0.05253	48.64
				Modified Epoxy Acrylate Resin	186511-06-8	0.00612	5.67
				C.I pigment blue 15	147-14-8	0.00006	0.06
				Silicon dioxide	7631-86-9	0.00318	2.94
				Barium Sulfate	7727-43-7	0.00002	0.02
				3-methoxy-3-methylbutylacetate	103429-90-9	0.00100	0.93
				Organic yellow pigment	Trade secret	0.00006	0.06
				Dipropylene glycol monomethyl ether	34590-94-8	0.00055	0.51
				Heavy Aromatic Solvent naphtha	64742-94-5	0.00185	1.71
				Talc	14807-96-6	0.00264	2.44
				Gold	7440-57-5	0.00015	0.14
				Palladium	7440-05-3	0.00015	0.14
				Nickel	7440-02-0	0.00188	1.74
2	Solder Paste	Alloy	0.0043	Sn	7440-31-5	0.00409	95.00
				Sb	7440-36-0	0.00022	5.00
3	Epoxy		0.0007	Di-ester resin	non-disclosure	0.00007	0.10
				Functionalized ester	non-disclosure	0.00007	0.10
				Silver	7440-22-4	0.00056	0.80
4	Passive/Active Components		0.2272	Ni Oxide	1313-99-1	0.01946	8.57
				Cu Oxide	1317-38-0	0.00655	2.88
				Zn Oxide	1314-13-2	0.02964	13.04
				Fe Oxide	1309-37-1	0.10800	47.53
				iron Powder (Fe)	7439-89-6	0.00316	1.39
				Copper (Cu)	7440-50-8	0.04622	20.34
				Nickel (Ni)	7440-02-0	0.00133	0.58
				Tin (Sn)	7440-31-5	0.00332	1.46
Ceramic (Ba Compounds)	12047-27-7	0.00952	4.19				
5	Active IC's	Silicon	0.0037	Silicon	7440-21-3	0.00370	100.00
6	Wire	Gold	0.0070	Au	7440-57-5	0.00700	99.99
7	Solder Ball		0.0523	Sn	7440-31-5	0.05047	96.50
				Ag	7440-22-4	0.00157	3.00
				Cu	7440-50-8	0.00026	0.50
8	Encapsulation	Epoxy Resin	0.6890	Fused Silica	60676-86-0	0.53191	77.20
				Epoxy Resin	non-disclosure	0.06132	8.90
				Phenol Resin	non-disclosure	0.06132	8.90
				Crytalline Silica	14808-60-7	0.02067	3.00
				Carbon Black	1333-86-4	0.00345	0.50
				Metal Hydroxide	non-disclosure	0.01034	1.50
Total Package Weight			1.0922				

Note: Composition derived from MSDS and material C of C from Vendors; Component Weight based on assembly of generic parts